Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	17-12-2022
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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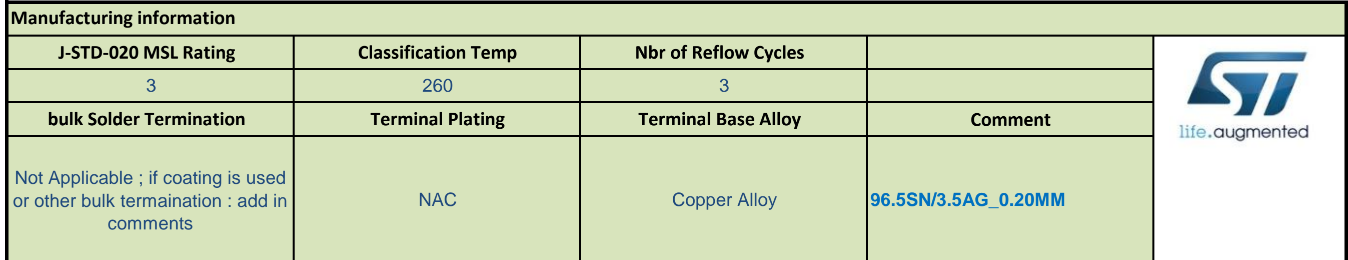
Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32G0B1RBI3N STM32G0B1RBI3NTR	232I*467XXXZ	A	9991	17-12-2022
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	34.40	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	NAC	Copper Alloy	**96.5SN/3.5AG_0.20MM**	

Package Designator	**Size**	**Nbr of instances**	**Shape**	
BGA	5x5	64	bulk solder	
Comment	Package : A019 UFBGA 5X5X0.6 64L P 0.5 MM 8526322			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**232I*467XXXZ**				6000000.0	999999.3
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	1.457	mg	supplier	die	Silicon (Si)	7440-21-3		1.120	mg	768703	32558
				supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	10981	465
				supplier	metallization	Copper (Cu)	7440-50-8		0.143	mg	98147	4157
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.046	mg	31572	1337
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1373	58
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	686	29
				supplier	Passivation	Silicon Nitride	12033-89-5		0.036	mg	24708	1047
				supplier	Passivation	Silicon Oxide	7631-86-9		0.093	mg	63830	2703
Substrate_A283140	M-011 Other inorganic materials	11.990	mg	supplier	BT-substrate	Thermosetting resin (Including filler)	Undisclosed		0.959	mg	80000	27884
					BT-substrate	Glass cloth	65997-17-3		3.837	mg	320000	111535
					BT-substrate	Copper foil	7440-50-8		4.316	mg	360000	125477
					BT-substrate	3-methoxy-3-methylbutylacetate	103429-90-9		0.600	mg	50000	17427
					BT-substrate	Morpholine derivative	Trade secret		0.120	mg	10000	3485
					Solder mask	Barium Sulfate	7727-43-7		1.439	mg	120000	41826
					Solder mask	Talc containing no asbestiform fibers	14807-96-6		0.060	mg	5000	1743
					Solder mask	Dipropylene glycol monomethyl ether	34590-94-8		0.659	mg	55000	19170
Die Attach ATB-125-12 (30)	M-011 Other inorganic materials	2.552	mg	supplier	film	Butadiene, acrylonitrile polymer, carboxy-termi	68610-41-3		1.781	mg	697750	51763
					film	Formaldehyde, polymer with (chloromethyl)ox	37382-79-9		0.665	mg	260750	19344
					film	Dapsone	80-08-0		0.102	mg	40000	2967
					film	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.002	mg	750	56
					film	Reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.002	mg	750	56
Bonding wire (Cu 0.8mils)	Precious metals	0.200	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.193	mg	965500	5613
					Bonding wire	Palladium (Pd)	7440-05-3		0.006	mg	31000	180
					Bonding wire	Gold (Au)	7440-57-5		0.001	mg	3500	20
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	16.645	mg	supplier	Molding Compound	Epoxy resin	Trade secret		0.666	mg	40000	19355
					Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		14.981	mg	900000	435480
					Molding Compound	Phenol resin	Trade secret		0.932	mg	56000	27097
					Molding Compound	Carbon Black	1333-86-4		0.067	mg	4000	1935
Solder balls (96.5SN/3.5AG_0.20MM)	Solder	1.556	mg	supplier	Solder	Tin (Sn)	7440-31-5		1.502	mg	965000	43649
					Solder	Silver (Ag)	7440-22-4		0.054	mg	35000	1583